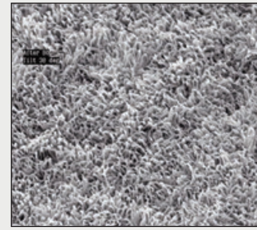
內層連結技術
Inner Layer Bonding Technology

Black Oxide – CIRCUPOSIT™ PB 484 Oxide 黑化製程

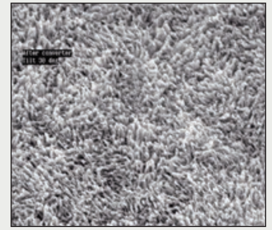
For Traditional Applications 應用於傳統壓合製程
Advantages 優點

- Leading market share in Japan, USA, SEA and China markets
  在日本,美國,東南亞及中國擁有高市佔率
- Wide application range and compatible with all laminate types
  寬廣的操作範圍並適用於各種類型的板材
- Best performance for high layer count applications
  在多層板壓合應用上,有最佳的信賴度表現
- High peel strength on high Tg epoxy based laminates
  應用在高Tg板材上有高抗剝離強度的表現
- Most stable process control and long bath life
  藥水操控穩定性高,槽液壽命較長

SEM Comparison
電子顯微鏡下比較



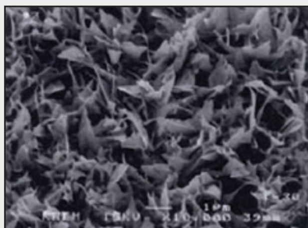
Before Converter
還原前



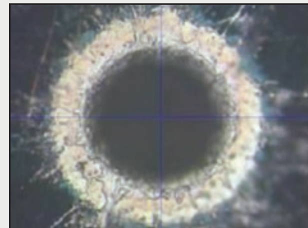
After Converter
還原後

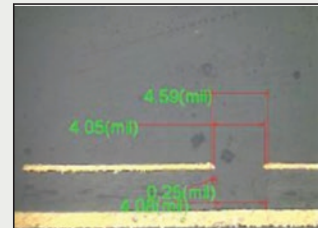
For Direct Laser Drilling Application in HDI 應用於HDI之直接雷射鑽孔製程
Advantages 優點

- Simplifies HDI process, leading to effective cost saving
  簡化HDI製程,可有效降低成本
- Excellent microvia shape in hole formation
  具有良好的盲孔真圓度及盲孔孔型
- Reduces failures in hole registration
  減少對位不良之現象
- Improves microvia yield rate, especially for smaller via diameters
  改善盲孔的生產良率,特別針對小孔徑盲孔
- Most stable process control and long bath life
  藥水操控穩定性高,槽液壽命較長



Compatible with DLD process
適用於直接電射鑽孔的黑化結構





Excellent microvia shape in hole formation
具有良好的盲孔真圓度及盲孔孔型

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